



TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
EN9-99-080

In Re Application Of: Caletka, et al.

Serial No.
09/438,037

Filing Date
11/10/1999

Examiner
Mitchell, J.

Group Art Unit
2827

Title: **PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA PACKAGES AND A METHOD OF FORMING THE INTERCONNECTIONS**

TO THE COMMISSIONER OF PATENTS AND TRADEMARKS:

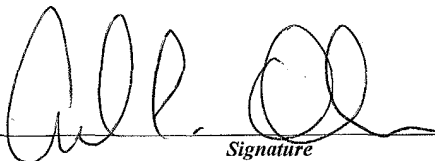
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Amendment (10 pages)
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in the above identified application.

- ☒ No additional fee is required.
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Caletka, et al.) Examiner: Mitchell, J.

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J. McWilliam
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AMENDMENT under 37 C.F.R. §1.116(a)

Sir:

In response to the Office Action mailed June 20, 2002,
please amend the above-identified patent application as follows:

IN THE SPECIFICATION:

Please delete the paragraph beginning on page 7, line 14
through page 8, line 5, and insert the following:

--Fig. 3 shows the second surface 18 of the chip carrier 14
(refer to Fig. 1) covered with a mask 26. Similarly, Fig. 4
shows the first surface 24 of the board 20 covered with a mask
28. The masks 26, 28 have elongated non-circular, oblong, oval,
or elliptical openings 30 located over the conductive pads 16,
22. As illustrated in Fig. 5, the elongated openings 30 within

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